

AMENDMENTS TO THE ABSTRACT

Please replace the Abstract on page 52 with the following replacement paragraph:

-- [Solution means] ~~The~~A process for producing a printed wiring board ~~of the invention comprises a step of~~comprises the steps of depositing a base metal on at least one surface of an insulating film to form a base metal layer and further depositing copper or a copper alloy to form a conductive metal layer, ~~a step of selectively~~then removing a surface metal layer, which is formed through the above step, by etching to form a wiring pattern, and ~~a step of~~then treating the base metal layer with a treating liquid capable of dissolving and/or passivating the metal that forms the base metal layer. The printed wiring board ~~of the invention~~so provided comprises an insulating film and a wiring pattern formed on at least one surface of the insulating film, ~~said the wiring pattern comprising~~including a base metal layer deposited on the insulating film surface and a conductive metal layer, ~~said the base metal layer for forming the wiring pattern being protruded~~protrudes in a widthwise direction more than the conductive metal layer for forming the wiring pattern. ~~—[Effect] According to the present invention, most of the metal that forms the base metal layer can be removed, and the base metal layer forming metal remaining in a slight amount is passivated, so that migration significantly hardly occurs and a printed wiring board having extremely high reliability can be obtained.---~~